



AF 1756
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: Miwa KOZAWA et al.

Group Art Unit: 1756

Serial No.: 10/670,291

Examiner: Daborah Chako-Davis

Filed: September 26, 2003

Confirmation No.: 6427

For: RESIST PATTERN THICKENING MATERIAL, PROCESS FOR
FORMING RESIST PATTERN, AND PROCESS FOR
MANUFACTURING SEMICONDUCTOR DEVICE

Attorney Docket Number: 031181

Customer Number: 38834

AMENDMENT AFTER FINAL REJECTION

MAILSTOP: AF

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

Date: August 19, 2005

Sir:

This paper is filed in response to the Office Action dated May 20, 2005.

Amendments to the Claims begins on page 2 of this paper.

Remarks begin on page 7 of this paper.

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